



## Product Information Sheet

### EPO-TEK® 930-1

**Date:** July 2019  
**Rev:** V  
**No. of Components:** Two  
**Mix Ratio by Weight:** 100 : 4  
**Specific Gravity:** Part A: 1.40 Part B: 1.03  
**Pot Life:** 1 Day  
**Shelf Life- Bulk:** One year at room temperature  
**Shelf Life- Syringe:** Six months at -40°C

**Recommended Cure: 150°C / 1 Hour**

Minimum Alternative Cure(s):

*May not achieve performance properties listed below*  
150°C / 10 Minutes  
100°C / 4 Hours  
80°C / 6 Hours

#### NOTES:

- Container(s) should be kept closed when not in use.
- Filled systems should be stirred thoroughly before mixing and prior to use.
- Performance properties (rheology, conductivity, others) of the product may vary from those stated on the data sheet when bi-pak/syringe packaging or post-processing of any kind is performed. Epoxy's warranties shall not apply to any products that have been reprocessed or repackaged from Epoxy's delivered status/container into any other containers of any kind, including but not limited to syringes, bi-paks, cartridges, pouches, tubes, capsules, films or other packages.

**Product Description:** A two part, thermally conductive, electrically insulating epoxy. It can be used for heat sinking semiconductor devices, hybrid microelectronics, or optics. It is a lower viscosity and smaller particle size alternative to EPO-TEK® 930.

**Typical Properties:** Cure condition: 150°C / 1 Hour Different batches, conditions & applications yield differing results.

Data below is not guaranteed. To be used as a guide only, not as a specification. \* denotes test on lot acceptance basis

#### PHYSICAL PROPERTIES:

* Color (before cure):	Part A: White	Part B: Amber
* Consistency:	Smooth paste	
* Viscosity (23°C) @ 5 rpm:	60,000-80,000	cPs
Thixotropic Index:	3.8	
* Glass Transition Temp:	≥ 70	°C (Dynamic Cure: 20-200°C/ISO 25 Min; Ramp -10-200°C @20°C/Min)
Coefficient of Thermal Expansion (CTE):		
Below Tg:	28	x 10 <sup>-6</sup> in/in°C
Above Tg:	96	x 10 <sup>-6</sup> in/in°C
Shore D Hardness:	82	
Lap Shear @ 23°C:	1,636	psi
Die Shear @ 23°C:	≥ 10	Kg 3,556 psi
Degradation Temp:	415	°C
Weight Loss:		
@ 200°C:	0.09	%
@ 250°C:	0.50	%
@ 300°C:	1.31	%
Suggested Operating Temperature:	< 300	°C (Intermittent)
Storage Modulus:	793,194	psi
* Particle Size:	≤ 20	microns

#### ELECTRICAL AND THERMAL PROPERTIES:

Thermal Conductivity:	1.1	W/mK
Volume Resistivity @ 23°C:	≥ 1 x 10 <sup>13</sup>	Ohm-cm
Dielectric Constant (1KHz):	3.99	
Dissipation Factor (1KHz):	0.004	

This information is based on data and tests believed to be accurate. Epoxy Technology, Inc. makes no warranties (expressed or implied) as to its accuracy and assumes no liability in connection with any use of this product.

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